

EPCDESIGNTOOL_MD-EM

Mechanical Die for Electromigration Testing

EPCDESIGNTOOL_MD-EM are sized equivalent to EPC device [EPC2016C](#) with die size 2.1 mm x 1.6 mm.

These devices have internal metal layers shorted for electromigration reliability testing.

Figure 1: Die Photo for EPCDESIGNTOOL_MD-EM

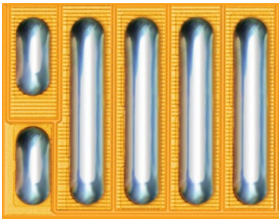
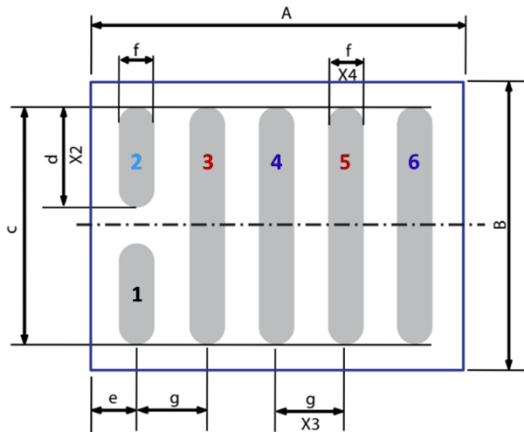


Figure 2: Die Outline (Solder Bar View)



DIM	MICROMETERS		
	MIN	Nominal	MAX
A	2076	2106	2136
B	1602	1632	1662
c	1379	1382	1385
d	577	580	583
e	235	250	265
f	195	200	205
g	400	400	400

Pad 1 is Gate;

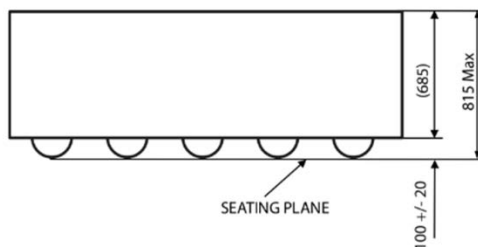
Pads 3, 5 are Drain

Pads 4, 6 are Source

Pad 2 is Substrate

NOTE: Drain and Source are internally shorted at Metal 1 to create a metal resistor

Figure 3: Side View



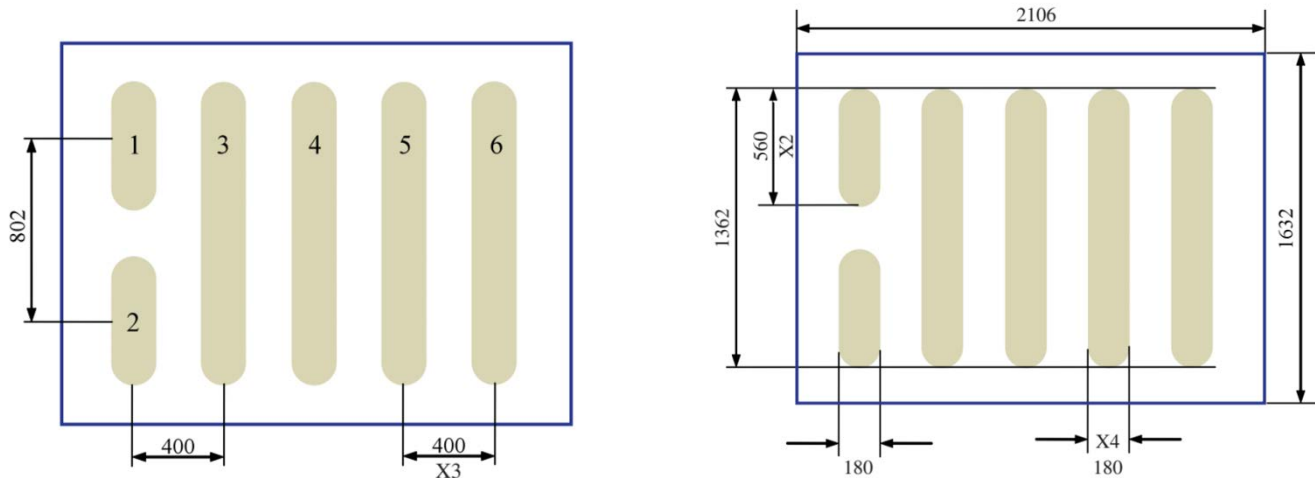
EPCDESIGNTOOL_MD-EM Mechanical Die for Electromigration Testing

Figure 4: Recommended Land Pattern (units in μm)

Land pattern is solder mask defined. Solder mask opening is $180\ \mu\text{m}$.

Recommended stencil should be 4mil ($100\ \mu\text{m}$) thick, must be laser cut,

Stencil opening can be per the bump drawing.



Pad 1 is Gate;

Pads 3, 5 are Drain

Pads 4, 6 are Source

Pad 2 is Substrate

Additional assembly resources available at epc-co.com/epc/DesignSupport/AssemblyResources.aspx

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